TRADE Aftorney Docket No.: 020964-003900US

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN **APPLICATION DATA SHEET (37 CFR 1.76)**

Title of Invention		SEMICONDUCTOR DEVICE PACKAGE DIEPAD HAVING FEATURES FORMED BY ELECTROPLATING						
As the below named inventor(s), I/we declare that:								
This declaration is directed to:								
	☐ The at	The attached application, or						
	Applic	Application No. 10/751,265, filed on January 2, 2004,						
	☐ as	amended on (if applica	ble);					
I/we believe that I/we am/are the original and first inventor(s) of the subject matter which is claimed and for which a patent is sought;								
I/we have reviewed and und amendment specifically refe	I/we have reviewed and understand the contents of the above-identified application, including the claims, as amended by any amendment specifically referred to above;							
I/we acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me/us to be material to patentability as defined in 37 CFR 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT International filing date of the continuation-in-part application.								
All statements made herein of my/our own knowledge are true, all statements made herein on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like are punishable by fine or imprisonment, or both, under 18 U.S.C. 1001, and may jeopardize the validity of the application or any patent issuing thereon.								
FULL NAME OF INVEN	TOR(S)							
Inventor 1 Hamza	a Yilmaz		Date: /	Anil 23 2004				
Signature:			Citizen of:	United States				
Inventor 2 Anthor	ny Chia		Date:	APRIL 21, DLY				
Signature:	Hute		Citizen of:	Singapore				
Inventor 3 Seishi	Fujimaki		Date:	4/23/2009				
Signature:	光正は	<u> </u>	Citizen of:	Japan				
Inventor 4 Xiaogu	ang Zeng		Date:	April 22, 04				
Signature: Zay	lingung		Citizen of:	Peoples Republic of China				
Additional inventors are being named on additional form(s) attached hereto.								

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POWER OF ATTORNEY and CORRESPONDENCE ADDRESS INDICATION FORM

Application Number	10/751,265			
Filing Date	January 2, 2004			
First Named Inventor	Yilmaz, Hamza			
Title	SEMICONDUCTOR DEVICE PACKAGE DIEPAD HAVING FEATURES FORMED BY ELECTROPLATING			
Art Unit	Unassigned			
Examiner Name	Unassigned			
Attorney Docket Number	020964-003900US			

I hereby a	ppoint:							
Practi	tioners asso	ociated with the Customer Number	203	350				
OR		•		 				
Practi	tioner(s) na	med below:						
		Name		Registration	Number			
				···				
as my/our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.								
Please reco	gnize or ch	nange the correspondence address for	the above	e-identified applic	ation to:			
	lress assoc	iated with the above-mentioned Custon	mer Numb	er:				
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☐ The add	iress assoc	ciated with Customer Number:						
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Firm <i>or</i> Individu	ıal Name							
Address								
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Country								
Telephone			Fax					
l am the: ☐ Applicant/Inventor.								
		rd of the entire interest. See 37 CFR 37 CFR 37 CFR 37 CFR 373(b) is enclosed. (Form PT						
SIGNATURE of Applicant or Assignee of Record								
Name	Rich	ARD J. KWLE		"				
Signature	9	Salle .			<u> </u>			
Date		4/24/2004		Telephone	415-8	306-6	199	
NOTE: Signatures of all the inventors or assignees of record of the entire interest or their representative(s) are required. Submit multiple forms if more than one signature is required, see below*.								
☐ *Total of		forms are submitted.						



STATEMENT UNDER 37 CFR 3.73(b) Applicant/Patent Owner: HAMZA YILMAZ et al. Application No./Patent No.: 10/751,265 Filed/Issue Date: January 2, 2004 Entitled: SEMICONDUCTOR DEVICE PACKAGE DIEPAD HAVING FEATURES FORMED BY **ELECTROPLATING** _GEM Services, Inc. , a Corporation (Name of Assignee) (Type of Assignee, e.g., corporation, partnership, university, government agency, etc.) states that it is: the assignee of the entire right, title, and interest; or 1. \boxtimes 2. an assignee of less than the entire right, title and interest. The extent (by, percentage) of its ownership interest is ____ in the patent application/patent identified above by virtue of either: A. An assignment from the inventor(s) of the patent application/patent identified above. The assignment was recorded in the United States Patent and Trademark Office at Reel _____, Frame _____, or for which a copy thereof is attached. B. A chain of title from the inventor(s), of the patent application/patent identified above, to the current assignee as shown below: 1. From: ___ To: The document was recorded in the United States Patent and Trademark Office at Reel _____, Frame _____, or for which a copy thereof is attached. The document was recorded in the United States Patent and Trademark Office at Reel _____, Frame _____, or for which a copy thereof is attached. To :_ The document was recorded in the United States Patent and Trademark Office at Reel _____, Frame _____, or for which a copy thereof is attached. Additional documents in the chain of title are listed on a supplemental sheet. Copies of assignments or other documents in the chain of title are attached. [NOTE: A separate copy (i.e., the original assignment document or a true copy of the original document) must be submitted to Assignment Division in accordance with 37 CFR Part 3, if the assignment is to be recorded in the records of the USPTO. See MPEP 302.8] The undersigned (whose title is supplied below) is authorized to act on behalf of the assignee. é CED PRESIDENT



Attorney Docket No.: 020964-003900US

ASSIGNMENT OF PATENT APPLICATION

JOINT

WHEREAS, Hamza Yilmaz of 20755 Trinity Avenue, Saratoga, CA 95057; Anthony Chia of Box 415, #7-105 Bedok North Ave. 2, Singapore, 460415 Singapore; Seishi Fujimaki of 4-7C, JinQiao Garden TongZhuAnBan Road, Shanghai, Peoples Republic of China; Xiaoguang Zeng of Room: 802, No:31, Lane 1661 Changnin Road, Shanghai, Peoples Republic of China, hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention:

SEMICONDUCTOR DEVICE PACKAGE DIEPAD

HAVING FEATURES FORMED BY ELECTROPLATING

Filing Date:

January 2, 2004

Application No.:

10/751,265; and

WHEREAS, **GEM Services, Inc.**, a corporation of United States, located at 1550 Sheffield Avenue, San Jose, CA 95125, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Dated: MRIL 27, 04

Seishi Fujimaki

Dated: MRIL 27, 04

Xiaoguang Zeng